

INVENTOR INFORMATION

Inventor One Given Name:: HIROKAZU
Family Name:: HONDA
Postal Address Line One:: C/O NEC CORPORATION
Postal Address Line Two:: 7-1, SHIBA 5-CHOME, MINATO-KU
City:: TOKYO
Country:: JAPAN
City of Residence:: TOKYO
Country of Residence:: JAPAN
Citizenship Country:: JAPAN

CORRESPONDENCE INFORMATION

Correspondence Customer Number:: 000466
Name Line One:: YOUNG & THOMPSON
Address Line One:: 745 SOUTH 23RD STREET
Address Line Two:: SECOND FLOOR
City:: ARLINGTON
State or Province:: VIRGINIA
Country:: U.S.A.
Postal or Zip Code:: 22202
Telephone:: 703-521-2297
Fax One:: 703-685-0573
Fax Two:: 703-979-4709

APPLICATION INFORMATION

Title Line One:: MULTILAYER INTERCONNECTION BOARD,
Title Line Two:: SEMICONDUCTOR DEVICE HAVING THE SAME,
Title Line Three:: AND METHOD OF FORMING THE SAME AS WELL
Title Line Four:: AS METHOD OF MOUNTING THE SEMICONDUCTOR
Title Line Five:: CHIP ON THE INTERCONNECTION BOARD
Total Drawing Sheets:: 158
Formal Drawings?: YES
Application Type:: UTILITY
Docket Number:: PF-2683/NEC/US/mh

REPRESENTATIVE INFORMATION

Representative Customer Number:: 000466

PRIOR FOREIGN APPLICATION

Foreign Application One:: 11-284566
Filing Date:: OCTOBER 5, 1999
Country:: JAPAN
Priority Claimed:: YES

Foreign Application Two:: 2000-057767
Filing Date:: MARCH 2, 2000
Country:: JAPAN
Priority Claimed:: YES